The IMAPS Northern California Chapter

presents

Disruptive Package Technologies ... Disruptive for Whom?

Speaker: Rich Rice, Senior VP Sales, ASE (US), Inc.

Date: Wednesday, June 3, 2009

Location: David's Restaurant
Banquet & Conference Facility
5151 Stars & Stripes Drive
Santa Clara, CA 95054

AGENDA:

11:30 AM – 12 PM	Registration & Networking
11:30 AM – 12:15 PM	Buffet Luncheon
12:15 PM – 1:00 PM	Speaker Presentation

Abstract: The term, "Disruptive Technologies", can be defined in many ways, and there are many historic examples of new technologies that have unexpectedly displaced established technologies. Relative to the semiconductor packaging industry, however, there is always much debate regarding the next big thing. With the industry being largely driven by the consumer electronics market, the semiconductor manufacturing community is constantly looking at innovative ways to meet the increasingly stringent size, performance, cost, and time-to-market requirements, as dictated by customers.
Clearly, there are many package technologies on the mass-production horizon, which could potentially be categorized as disruptive, such as TSV, embedded substrates, copper wire bonding, and fanout, to name but a few. But the real question is, to whom are these technologies disruptive? And why is this important to understand? Rich Rice will give consideration to these questions, and provide perspective on the impact of disruptive technologies across the entire semiconductor manufacturing supply chain.

Speaker Bio: Rich Rice is Senior Vice President of Sales for ASE (U.S.) Inc., with responsibility for the North America region. Appointed in 2003, Mr. Rice oversees field sales and applications engineering support necessary for achieving ASE's projected growth in the coming years. Prior to joining ASE, Mr. Rice spent over ten years at Amkor Technology, where he held various management roles, including Vice President of Sales and Vice President of Business Development. Previously, Mr. Rice performed engineering roles at Nara Technologies and National Semiconductor Corporation. Mr. Rice holds a BS degree in Agricultural Engineering from the University of Illinois.

Luncheon Fee

Members/General $20.00. Students (with ID) $10.00

Price includes lunch and program. Please email Gina Love at glove@cctlaser.com to reserve your space today! Registrations will be confirmed via email. We accept cash and checks at the door.